

FIG. 1

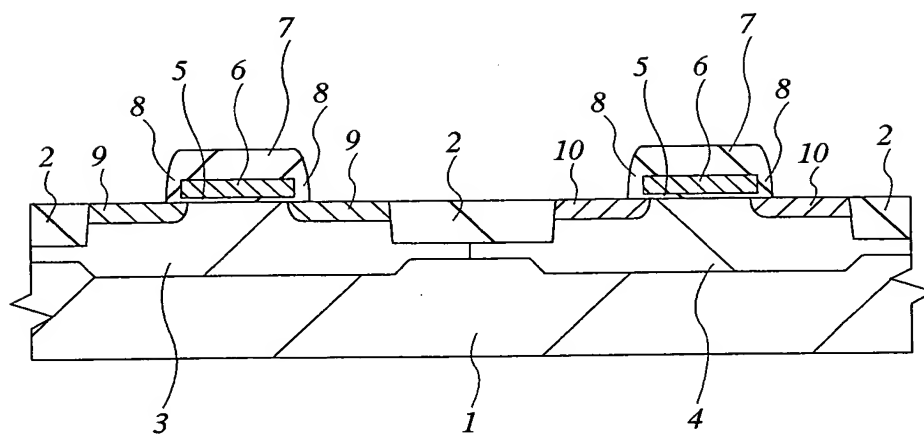
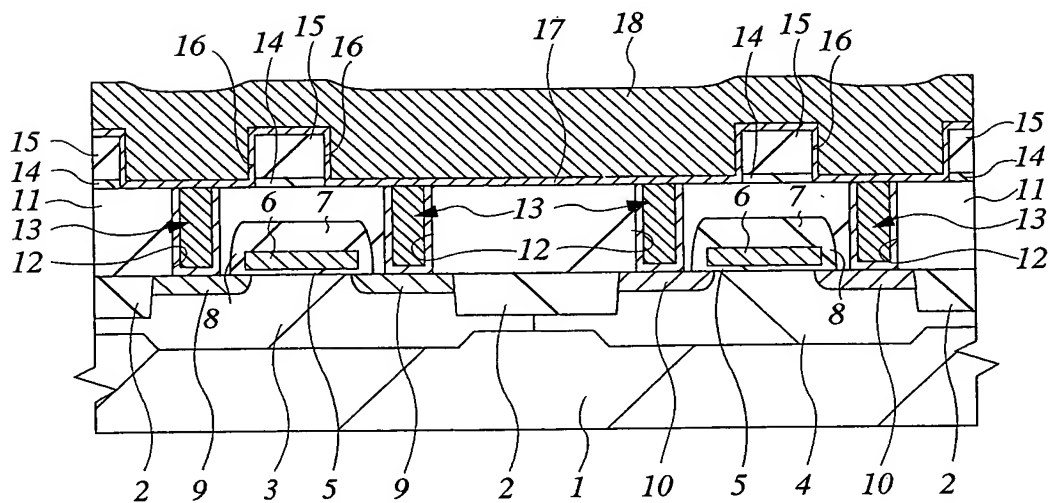


FIG. 2





A detailed cross-sectional diagram of a semiconductor device. The structure consists of several horizontal layers. At the top, there are four rectangular openings or windows. Below these, a layer contains horizontal bars or conductive paths. Further down, another layer features vertical structures resembling pillars or vias. The bottom portion of the device shows a substrate with various internal layers and a base surface. Numerous numerical labels (e.g., 1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 19, 20, 21, 22, 23, 24, 25, 26, 27) are used throughout the diagram to identify specific components, layers, and structural features.

FIG. 7

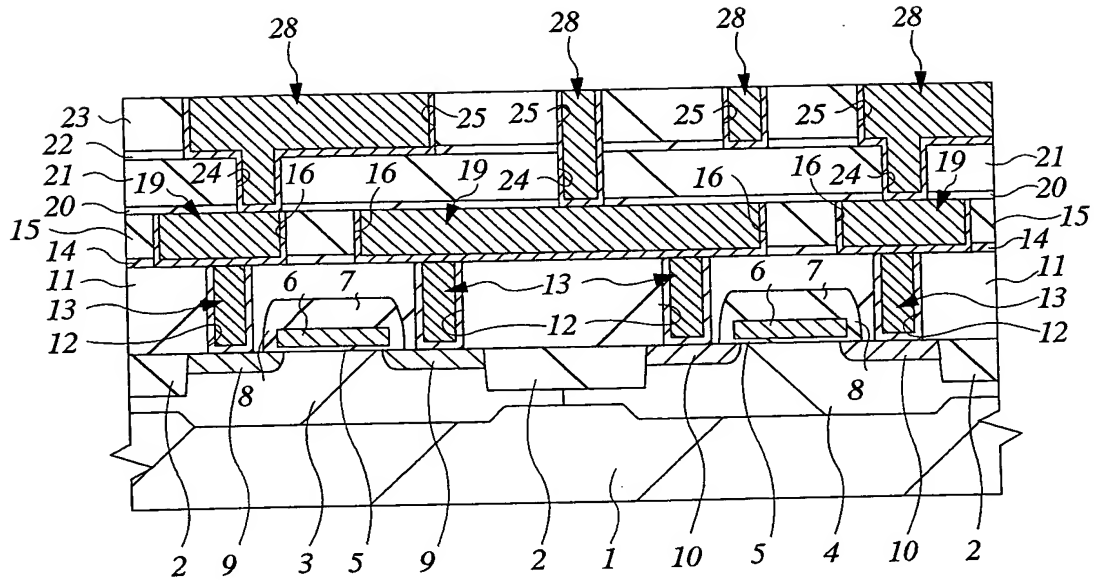


FIG. 8

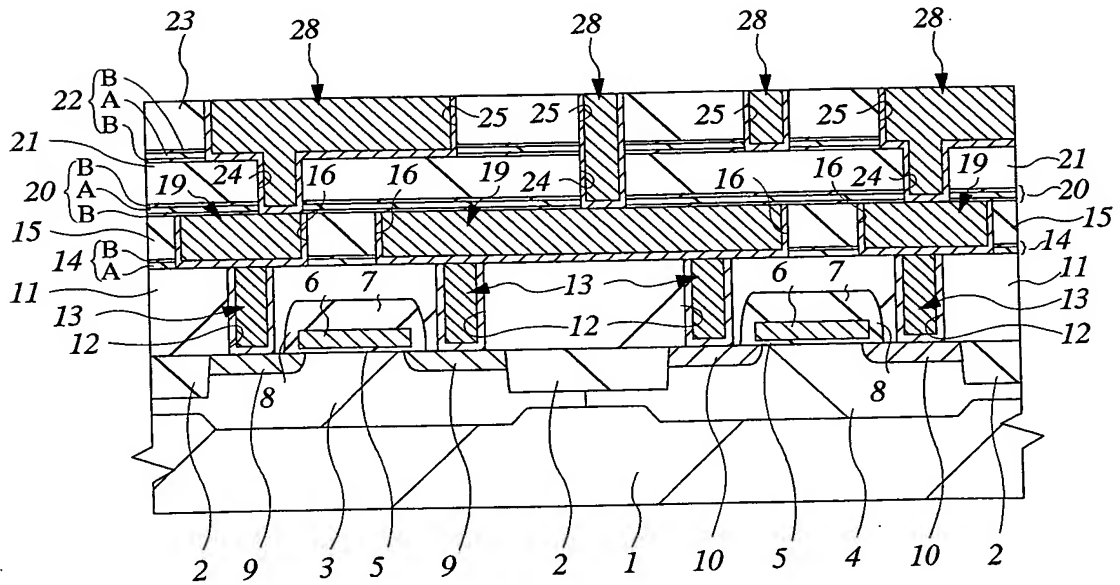


FIG. 9

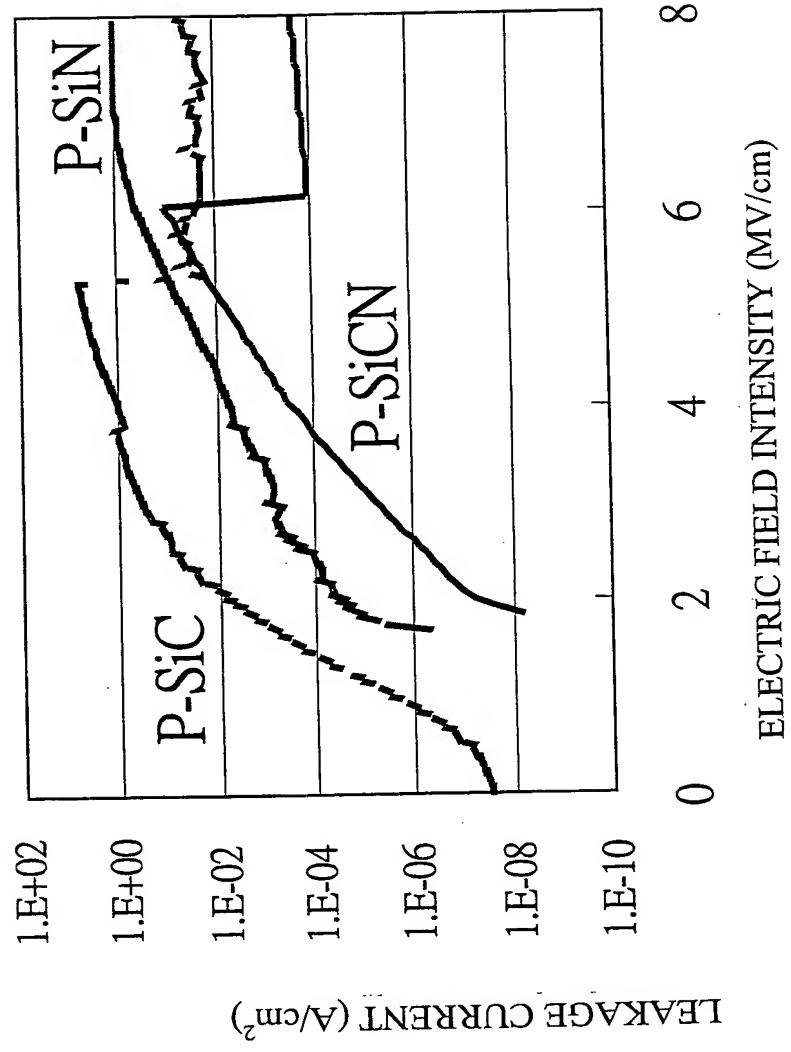


FIG. 10

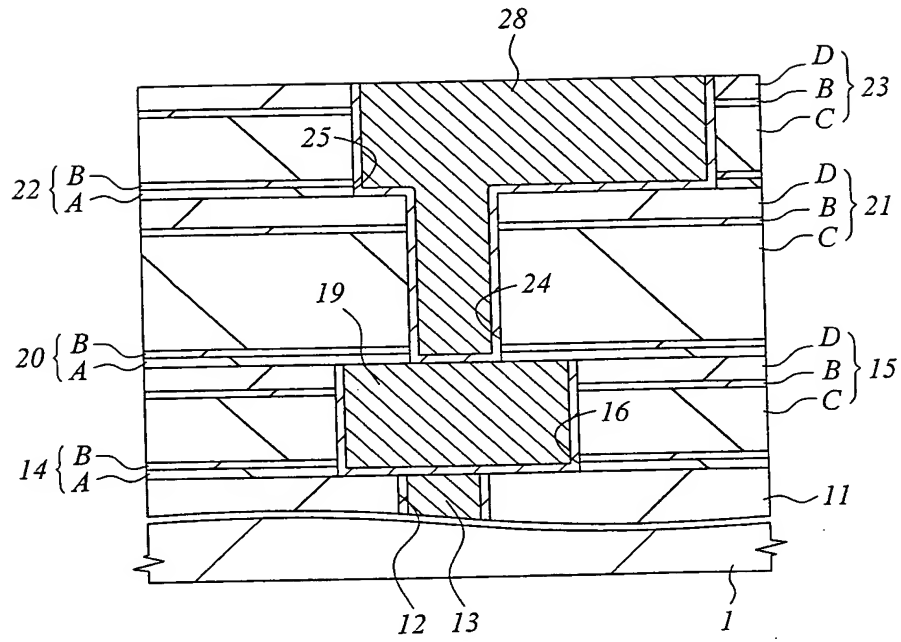


FIG. 11

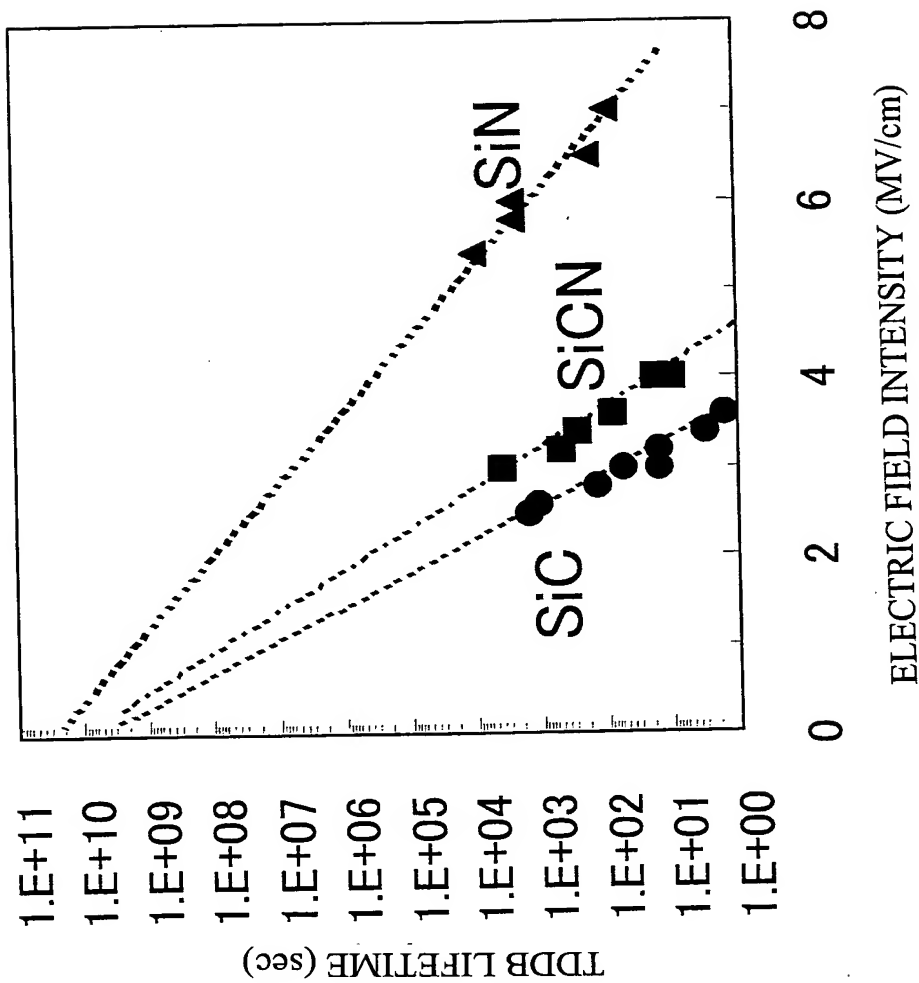


FIG. 12

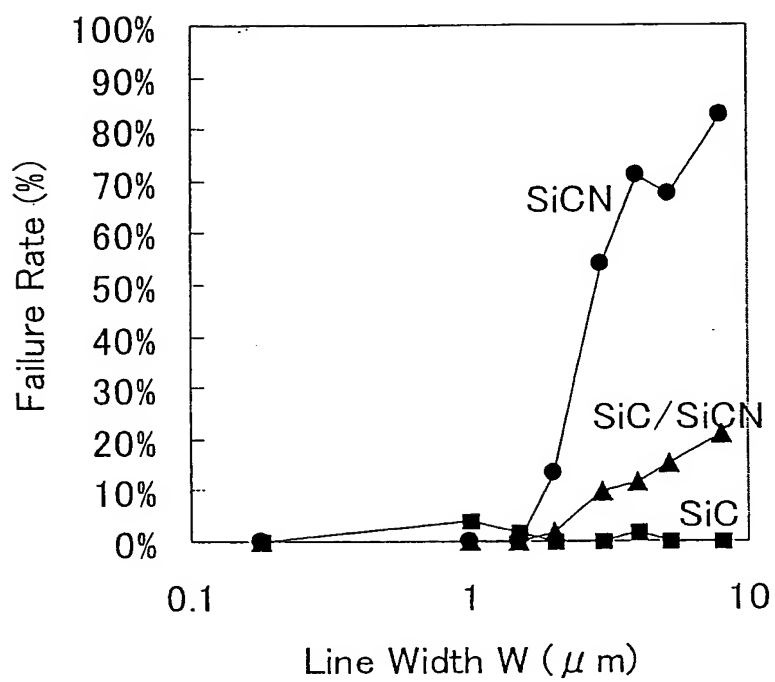


FIG. 13

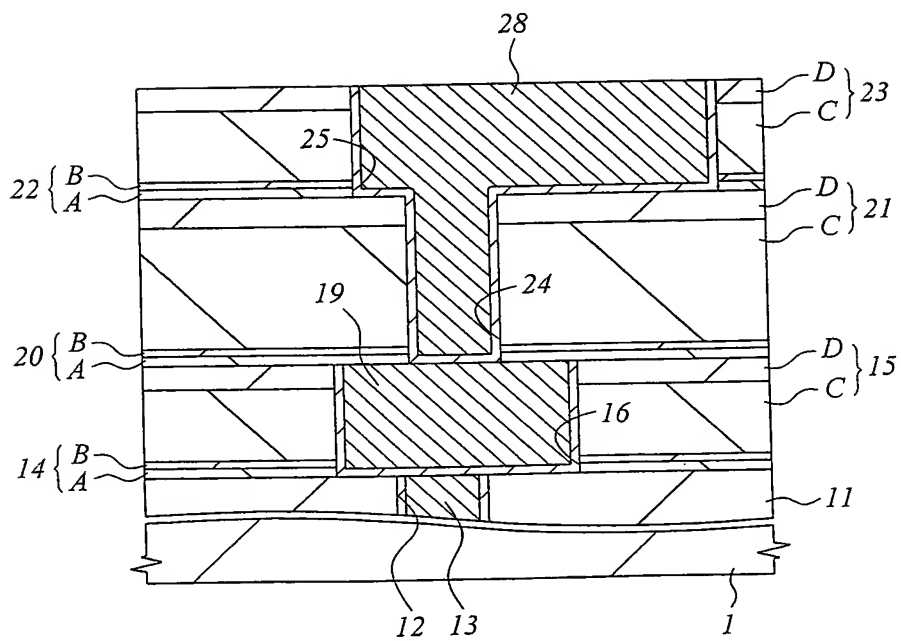




FIG. 14

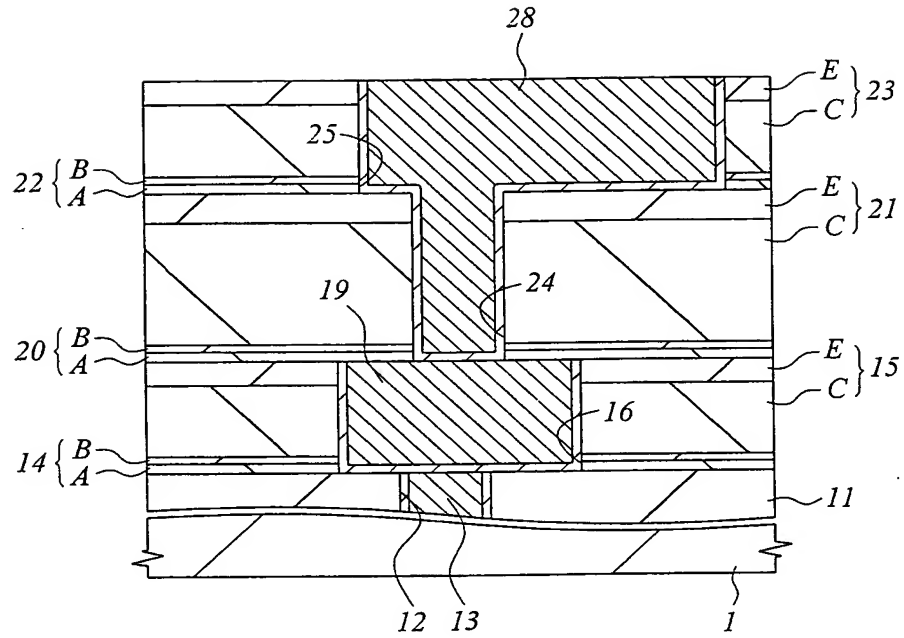


FIG. 15

